CLAIMS

1. A photosensitive resin composition comprising a carboxyl group-containing resin, a thermosetting resin, a photosensitive monomer, and an organic solvent, wherein,

the carboxyl group-containing resin comprises a carboxyl group-containing photosensitive resin obtained by bringing a bifunctional or more polyfunctional (solid) epoxy resin into reaction with (meth)acrylic acid, and adding a dibasic acid anhydride to the hydroxyl group present in a side chain; and

when it is assumed that the viscosity of the photosensitive resin composition at 25°C is A (dPa·s), and that the volume-specific resistance value of the photosensitive resin composition at 25°C is B (MΩ), and when the viscosity of the photosensitive resin composition is adjusted to A_1 = 5.0 (dPa·s) and A_2 = 1.5 (dPa·s) using propylene glycol monomethyl ether, the volume-specific resistance value B_1 (MΩ) given at A_1 and the volume-specific resistance value B_2 (MΩ) given at A_2 satisfy the following formula:

$$1.4 \leq (A_1 - A_2)/(B_1 - B_2) \leq 40.$$

2. The photosensitive resin composition according to claim 1, further comprising a quaternary ammonium salt compound.

3. The photosensitive resin composition according to claim 2, wherein the quaternary ammonium salt compound is at least one selected from tetrabutylammonium bromide and tetrapropylammonium bromide.

4. The photosensitive resin composition according any one of claims 1 to 3, wherein the organic solvent is at least one selected from the group consisting of diethylene glycol monomethyl ether acetate, diethylene glycol monoethyl ether acetate, propylene glycol monomethyl ether acetate, dipropylene glycol monomethyl ether, and propylene glycol monomethyl ether.

5. The photosensitive resin composition according to any one of claims 1 to 4, for use in the coating with a spray coater.

6. The photosensitive resin composition according to any one of claims 1 to 5, for use in the formation of a solder resist.

7. A method of producing a printed wiring board comprising a solder resist layer, comprising:

applying the photosensitive resin composition according to any one of claims 1 to 6 to a board using a spray coater; exposing the composition; and curing the composition under at least any one of light and heat to form

the solder resist layer.